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2000



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Akira Nagakura
Serial No. : 09/920,925
Filed : August 2, 2001
Title : BACK COVER FOR LAMP BODY

Art Unit : 2875
Examiner : Thomas M Sember

MAIL STOP AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT IN REPLY TO ACTION OF SEPTEMBER 15, 2003

Please amend the above-identified application as follows:

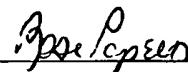
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I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

November 11, 2003

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5. (Currently Amended) A method for forming a waterproof seal about a power supply cord in a back cover of a lamp body comprising:

inserting the power supply cord through a cord insertion hole in the back cover of a lamp body;

forming a first resin mold layer in a cylindrical outer wall that forms a well that surrounds the cord insertion hole with a predetermined amount of soft synthetic resin; and

laminating a second resin mold layer on the first resin mold layer.

6. (Previously Presented) An apparatus, comprising:

a cover that includes a hole and a wall to form a well surrounding the hole;

a cord passed through the hole;

a first resin mold layer formed within the well and surrounding the cord to cover the hole, said first layer having a first surface adhered to the cover and having a second surface opposite to the first surface; and

a second resin mold layer laminated to the second surface of the first mold layer.

7. (Previously Presented) The apparatus of claim 6, wherein the cover is made of polypropylene, the first resin mold layer is made of at least one of an olefin based and a synthetic resin based synthetic rubber hot melt agent, and the second resin mold layer is made of a polyamide based hot melt agent.

8. (Previously Presented) The apparatus of claim 6, wherein the a ratio of thickness between the first mold resin layer and the second mold resin layer is two to one.

9. (Previously Presented) The apparatus of claim 7, wherein the a ratio of thickness between the first mold resin layer and the second mold resin layer is two to one.